



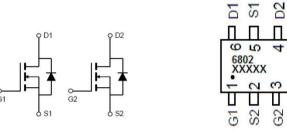
MJ N-Channel Enhancement Mode Power MOSFET

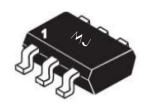
Description

The MJ6802 uses advanced trench technology to provide excellent $R_{\text{DS}(\text{ON})}$ and low gate charge. This device is suitable for use as a load switch or in PWM applications.

General Features

- ♦ $V_{DS}=30V,I_{D}=3.5A$ $R_{DS(ON)}<70m\Omega$ @ $V_{GS}=4.5V$ $R_{DS(ON)}<45m\Omega$ @ $V_{GS}=10V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package





Schematic diagram

Marking and pin Assignment

Application

Load switch

Battery protection

Power management

SOT23-6L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
6802	MJ6802	SOT-23-6L	Ø 180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	VDS	30	V	
Gate-Source Voltage	Vgs	±20	V	
Drain Current-Continuous	lo	3.5	А	
Drain Current-Pulsed (Note 1)	IDM	20	А	
Maximum Power Dissipation	Po	1.2	W	
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 150	°C	

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	Ra.ia	104	°C/W
Thermal Resistance, building to Ambient	INOJA	104	_ C/ V V





Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'					
Drain-Source Breakdown Voltage	BVpss	V _{GS} =0V I _D =250µA	30	33	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	1.2	1.5	2.2	V
Davis Course On Chata Daviston	D	Vgs=10V, Ip=3.5A	-	36	45	mΩ
Drain-Source On-State Resistance	Rds(on)	V _{GS} =4.5V, I _D =2A	-	59	70	mΩ
Forward Transconductance	grs	V _{DS} =5V,I _D =3.5A	-	12	-	S
Dynamic Characteristics (Note 4)	'		1	1		
Input Capacitance	Clss		-	170	-	PF
Output Capacitance	Coss	V _{DS} =15V,V _{GS} =0V F=1.0MHz	-	35	-	PF
Reverse Transfer Capacitance	Crss		-	23	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}		-	4.5	-	nS
Turn-on Rise Time	tr	V _{DD} =15V,R _L =4.2Ω	-	1.5	-	nS
Turn-Off Delay Time	t _{d(off)}	Vgs=10V,Rgen=3Ω	-	18.5	-	nS
Turn-Off Fall Time	t _f	-	-	15.5	-	nS
Total Gate Charge	Qg		-	4.0	-	nC
Gate-Source Charge	Qgs	V _{DS} =15V,I _D =3.5A V _{GS} =10V	-	0.75	-	nC
Gate-Drain Charge	Qgd	-	_	0.65	-	nC
Drain-Source Diode Characteristics	I	1			I	<u>I</u>
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =3.5A	-	0.8	1.2	V
Diode Forward Current (Note 2)	ls		_	_	3.5	А

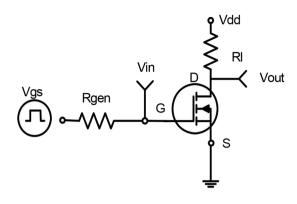
Notes:

- $\textcircled{1} \ \ \mathsf{Repetitive} \ \ \mathsf{Rating:} \ \ \mathsf{Pulse} \ \ \mathsf{width} \ \ \mathsf{limited} \ \ \mathsf{by} \ \ \mathsf{maximum} \ \mathsf{junction} \ \ \mathsf{temperature}.$
- ② Surface Mounted on FR4 Board, t≤10sec.
- ③ Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%.
- 4 Guaranteed by design, not subject to production





Typical Electrical and Thermal Characteristics



 $t_{d(on)}$ $t_{d(off)}$ t_{d

Figure 1 Switching Test Circuit

Figure 2 Switching Waveforms

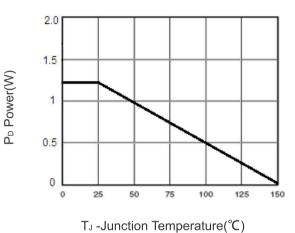
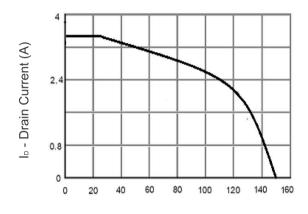


Figure 3 Power Dissipation



T_J -Junction Temperature(°C)
Figure 4 Drain Current

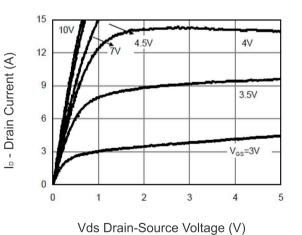


Figure 5 Output Characteristics

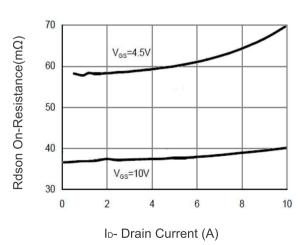
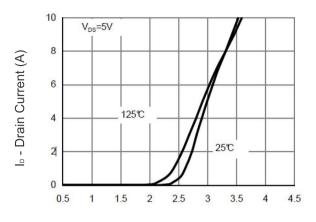


Figure 6 Drain-Source On-Resistance

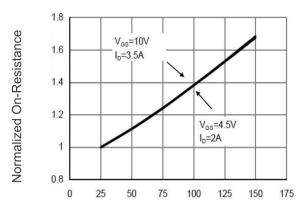


Rdson On-Resistance(Ω)

Vgs Gate-Source Voltage (V)



Vgs Gate-Source Voltage (V)
Figure 7 Transfer Characteristics



T_J -Junction Temperature(°C)
Figure 8 Drain-Source On-Resistance

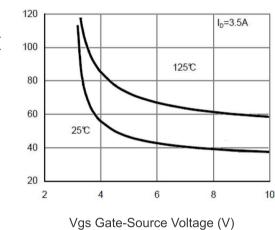


Figure 9 Rdson vs Vgs

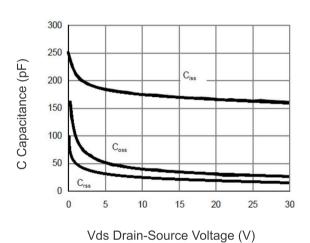
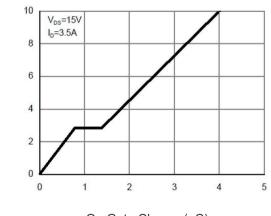
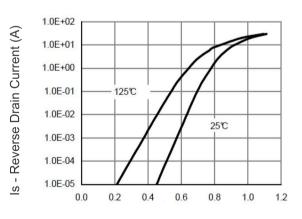


Figure 10 Capacitance vs Vds

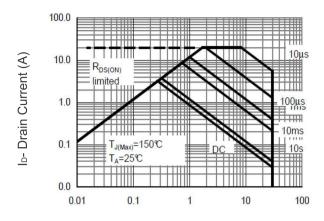


Qg Gate Charge (nC)
Figure 11 Gate Charge



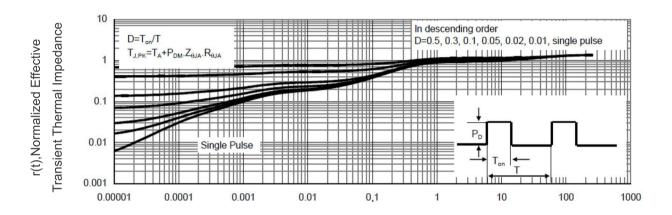
Vsd Source-Drain Voltage (V)
Figure 12 Source- Drain Diode Forward





Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area



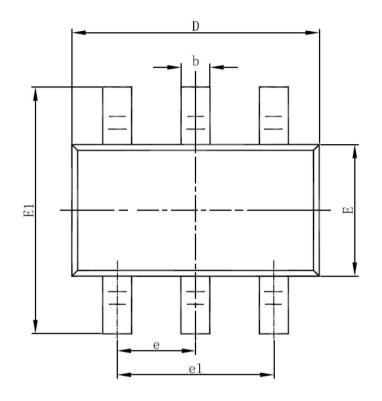
Square Wave Pluse Duration(sec)

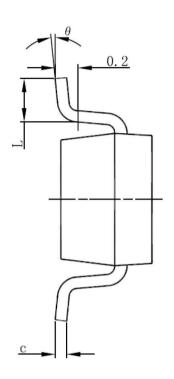
Figure 14 Normalized Maximum Transient Thermal Impedance

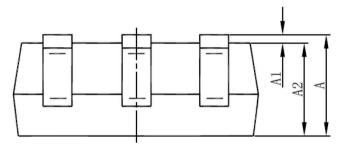




SOT23-6L Package Information







C	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	





Attention:

Any and all MJ power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MJ power representative nearest you before using any MJ power products described or contained herein in such applications.

MJ power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MJ power products described or contained herein.

Specifications of any and all MJ power products described or contained herein stipulate the erformance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

MJ power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all MJ power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or therwise, without the prior written permission of MJ power Semiconductor CO.,LTD.

Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MJ power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MJ power product that you intend to use.

This catalog provides information as of Sep.2010. Specifications and information herein are subject to change without notice.